AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-4 (canceled).

Claim 5 (currently amended): A method of manufacturing an external force detection sensor ~~according to claim 4~~, comprising interposing an etching stop layer comprised of an electrically conductive material between an element substrate and a dummy support substrate to support the element substrate through-hole dry etching of the element substrate to form a sensor element; wherein the dummy support substrate and the etching stop layer are removed after the sensor element is formed and, after that, a support substrate with a recessed part formed therein is arranged on a back surface side of said element substrate such that the recessed part of said support substrate is arranged opposite to the sensor element and, then the support substrate is joined with the element substrate.

Claims 6-8 (canceled).

Claim 9 (previously presented): A method of manufacturing an external force detection sensor according to claim 5, wherein the element substrate is formed of a silicon material, the support substrate is formed of a glass material, and the element substrate is anodically joined with the support substrate.

Claim 10 (currently amended): A method of manufacturing an external force detection sensor according to claim 5 4,

wherein the etching stop layer is formed of an electrically conductive material whose etch selectivity which is the ratio of the dry-etch rate of an element substrate to the dry-etch rate of an etching stop layer is not less than 1.

Claim 11 (currently amended): A method of manufacturing an external force detection sensor according to claim 5 4, wherein the sensor element is a movable element.

Claim 12 (original): A method of manufacturing an external force detection sensor according to claim 10, wherein the etching stop layer is made of titanium or aluminum.

Claims 13-20 (canceled).